

PLASTIC ENCAPSULATED MICROCIRCUITS AND THEIR RELIABILITY EVALUATION

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The paper gives an overview of the present situation in the domain, the front line in the battle for the best products. After a short introduction, the main problems arisen in reliability evaluation of monolithic integrated circuits, the evaluation itself and some new points of view concerning the dynamic life testing, screening and burn-in, accelerated tests, physics of failure of plastic encapsulated microcircuits (PEM) and process reliability are presented. Characterization techniques for $Hg_{1-x}Cd_xTe$ epilayers are mentioned.